

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
	80mΩ @ V _{GS} = 10V	4.1A
60V	100mΩ @ V _{GS} = 4.5V	3.6A

Description and Applications

This MOSFET is designed to minimize the on-state resistance $(R_{DS(on)})$ and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

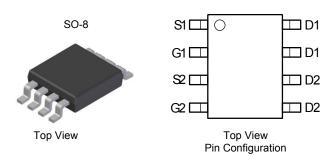
- Backlighting
- Power Management Functions
- DC-DC Converters

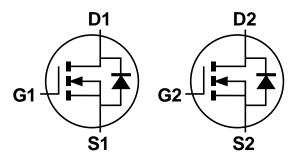
Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (Approximate)





Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN6070SSD-13	SO-8	2,500/Tape & Reel

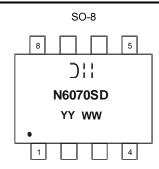
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



)|| = Manufacturer's Marking N6070SD = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 13 = 2013) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic Drain-Source Voltage Gate-Source Voltage			Symbol	Value	Units V	
			V _{DSS}	60		
			V _{GSS}	±20	V	
Continuous Drain Current (Note C) // - 10//	Steady State	T _A = +25°C T _A = +70°C	ID	3.3 2.6	А	
Continuous Drain Current (Note 6) V_{GS} = 10V	t<10s	T _A = +25°C T _A = +70°C	ID	4.1 3.4	А	
Maximum Continuous Body Diode Forward Current (Note 5)			Is	2.0	А	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	12	А	
Avalanche Current (Note 7) L=0.1mH			IAS	10	А	
Avalanche Energy (Note 7) L=0.1mH			E _{AS}	5.9	mJ	

Thermal Characteristics (@T_A= +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Total Power Dissipation (Note 5)		PD	1.2	W	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	104	°C/W	
mermai Resistance, Junction to Amplent (Note 5)	t<10s	$R_{ ext{ heta}JA}$	61	C/VV	
Total Power Dissipation (Note 6)		PD	1.5	W	
Thermal Registerion Junction to Ambient (Note 6)	Steady State	D	83	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	$R_{ heta}$ JA	50		
Thermal Resistance, Junction to Case	$R_{ ext{ heta}JC}$	14.5			
Operating and Storage Temperature Range		TJ. TSTG	-55 to +150	°C	

Electrical Characteristics (@TA= +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)	ii			ł		1
Drain-Source Breakdown Voltage	BV _{DSS}	60			V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	IDSS			1	μA	V _{DS} = 60V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}			±100	nA	V_{GS} = ±16V, V_{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(th)}	1.0	_	3.0	V	I _D = 250µA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance	D		68	80	mΩ	V _{GS} = 10V, I _D = 4.5A
	Rds (ON)	_	70	100	11122	V _{GS} = 4.5V, I _D = 3.5A
Diode Forward Voltage	V _{SD}	_	0.75	1.1	V	I _S = 12A, V _{GS} = 0V
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	_	588	—		V _{DS} = 30V, V _{GS} = 0V f= 1MHz
Output Capacitance	Coss	_	26.5	_	pF	
Reverse Transfer Capacitance	Crss	_	20	—		
Gate Resistance	Rg	_	1.5	_	Ω	Vgs= 0V, Vds= 0V, f=1MHz,
Total Gate Charge (V _{GS} = 4.5V) Q _q 5.6						
Total Gate Charge (V _{GS} = 10V)	Qg	_	12.3	_		$y_{1} = 20y_{1} + 20$
Gate-Source Charge	Q _{gs}	_	1.7	_	nC	V _{DS} = 30V, I _D = 3A
Gate-Drain Charge	Q _{gd}	_	1.9	_		
Turn-On Delay Time	t _{D(on)}	_	3.5	_		
Turn-On Rise Time	tr		4.1	_	-0	V _{DD} = 30V, V _{GS} = 10V
Turn-Off Delay Time	t _{D(off)}		35	_	nS	$R_L \cong 50\Omega, R_G \cong 20\Omega$
Turn-Off Fall Time	t _f		11	—	1	
Body Diode Reverse Recovery Time	trr	_	18	_	nS	I _S = 12A, dl/dt = 100A/µs
Body Diode Reverse Recovery Charge	Qrr	_	12	—	nC	I _S = 12A, dl/dt = 100A/µs

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
8. Short duration pulse test used to minimize self-heating effect.
9. Guaranteed by design. Not subject to product testing. Notes:



4.5 5

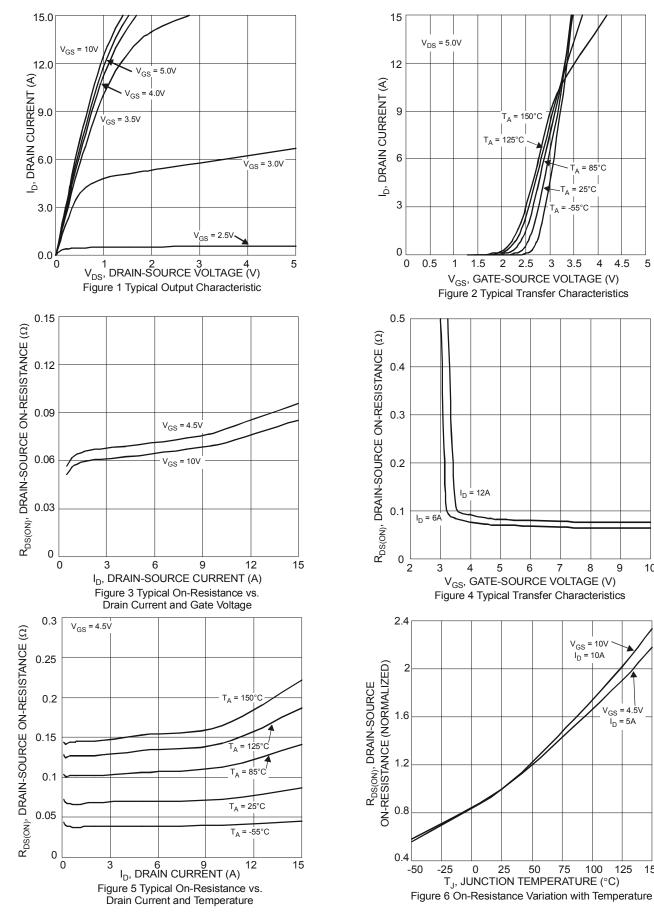
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= 4.5V

= 5A I_D

125

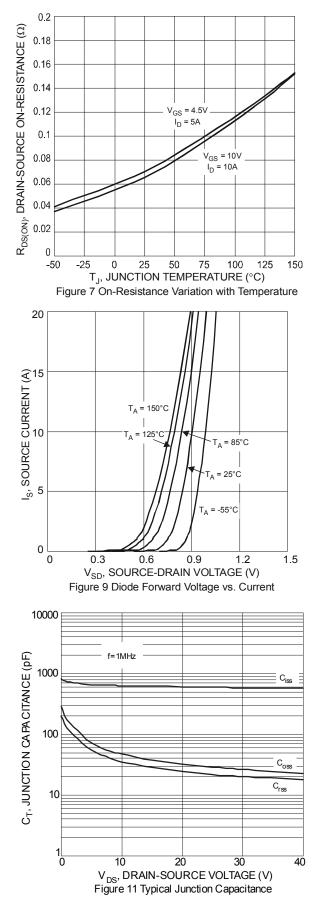
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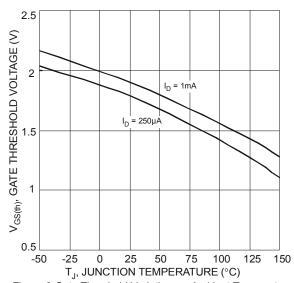


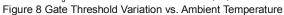
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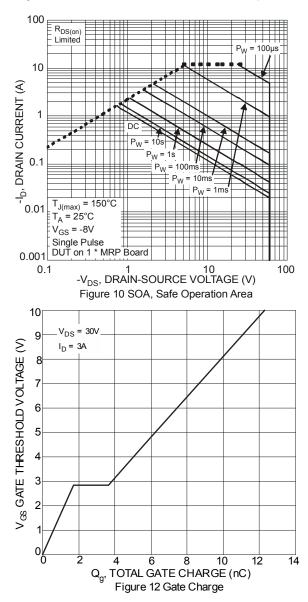




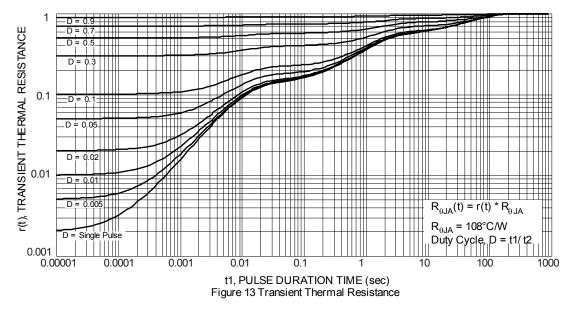






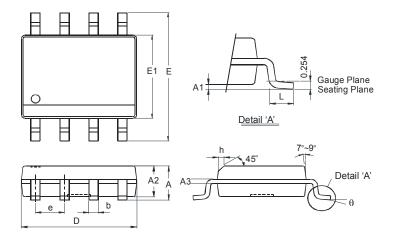






Package Outline Dimensions

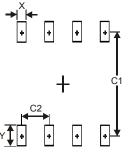
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



	SO-8				
Dim	Min	Max			
Α	-	1.75			
A1	0.10	0.20			
A2	1.30	1.50			
A3	0.15	0.25			
b	0.3	0.5			
D	4.85	4.95			
Е	5.90	6.10			
E1	3.85 3.95				
e	e 1.27 Typ				
h	- 0.35				
L	0.62	0.82			
θ	0° 8°				
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27

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